

LM148, LM248, LM348 QUADRUPLE OPERATIONAL AMPLIFIERS

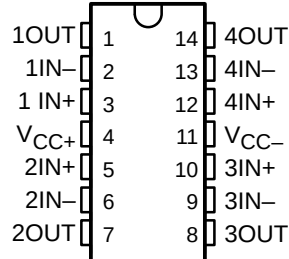
SLOS058C – OCTOBER 1979 – REVISED DECEMBER 2002

- μ A741 Operating Characteristics
- Low Supply-Current Drain . . . 0.6 mA Typ (per amplifier)
- Low Input Offset Voltage
- Low Input Offset Current
- Class AB Output Stage
- Input/Output Overload Protection
- Designed to Be Interchangeable With Industry Standard LM148, LM248, and LM348

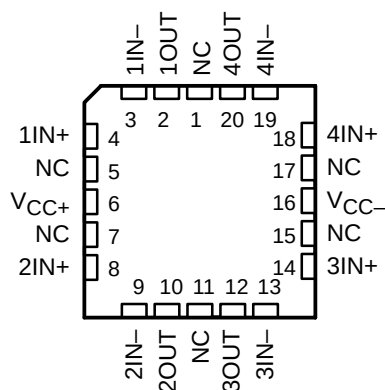
description/ordering information

The LM148, LM248, and LM348 are quadruple, independent, high-gain, internally compensated operational amplifiers designed to have operating characteristics similar to the μ A741. These amplifiers exhibit low supply-current drain and input bias and offset currents that are much less than those of the μ A741.

LM148 . . . J PACKAGE
LM248 . . . D OR N PACKAGE
LM348 . . . D, N, OR NS PACKAGE
(TOP VIEW)



LM148 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

ORDERING INFORMATION

T_A	V_{IOmax} AT 25°C	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	6 mV	PDIP (N)	Tube of 25	LM348N	LM348N
		SOIC (D)	Tube of 50	LM348D	LM348
			Reel of 2500	LM348DR	
		SOP (NS)	Reel of 2000	LM348NSR	LM348
–25°C to 85°C	6 mV	PDIP (N)	Tube of 25	LM248N	LM248N
		SOIC (D)	Tube of 50	LM248D	LM248
			Reel of 2500	LM248DR	
–55°C to 125°C	5 mV	CDIP (J)	Tube of 25	LM148J	LM148J
		LCCC (FK)	Tube of 50	LM148FK	LM148FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

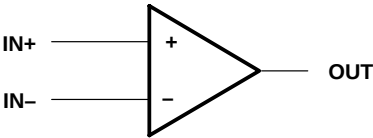
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LM148, LM248, LM348
QUADRUPLE OPERATIONAL AMPLIFIERS

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symbol (each amplifier)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Table with 2 columns: Parameter and Rating. Rows include Supply voltage (VCC+), Supply voltage (VCC-), Differential input voltage (VID), Input voltage (VI), Duration of output short circuit, Operating virtual junction temperature (TJ), Package thermal impedance (thetaJA), Package thermal impedance (thetaJC), Case temperature for 60 seconds, Lead temperature, and Storage temperature range.

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied.

- NOTES: 1. All voltage values, unless otherwise noted, are with respect to the midpoint between VCC+ and VCC-.
2. Differential voltages are at IN+ with respect to IN-.
3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or the value specified in the table, whichever is less.
4. The output may be shorted to ground or either power supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
5. Maximum power dissipation is a function of TJ(max), thetaJA, and TA. The maximum allowable power dissipation at any allowable ambient temperature is PD = (TJ(max) - TA)/thetaJA. Operating at the absolute maximum TJ of 150°C can affect reliability.
6. The package thermal impedance is calculated in accordance with JESD 51-7.
7. Maximum power dissipation is a function of TJ(max), thetaJC, and TC. The maximum allowable power dissipation at any allowable ambient temperature is PD = (TJ(max) - TC)/thetaJC. Operating at the absolute maximum TJ of 150°C can affect reliability.
8. The package thermal impedance is calculated in accordance with MIL-STD-883.

recommended operating conditions

Table with 4 columns: Parameter, MIN, MAX, UNIT. Rows include Supply voltage (VCC+) and Supply voltage (VCC-).

electrical characteristics at specified free-air temperature, $V_{CC\pm} = \pm 15$ V (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		LM148			LM248			LM348			UNIT		
				MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX			
V _{IO}	Input offset voltage	V _O = 0	25°C	1		5	1		6	1		6	mV		
			Full range			6			7.5			7.5			
I _{IO}	Input offset current	V _O = 0	25°C	4		25	4		50	4		50	nA		
			Full range			75			125			100			
I _{IB}	Input bias current	V _O = 0	25°C	30		100	30		200	30		200	nA		
			Full range			325			500			400			
V _{ICR}	Common-mode input voltage range		Full range	±12			±12			±12			V		
V _{OM}	Maximum peak output voltage swing	R _L = 10 kΩ	25°C	±12	±13		±12		±13		±12		±13		V
		R _L ≥ 10 kΩ	Full range	±12		±12		±12		±12		±12			
		R _L = 2 kΩ	25°C	±10	±12		±10		±12		±10		±12		
		R _L ≥ 2 kΩ	Full range	±10		±10		±10		±10		±10			
A _{VD}	Large-signal differential voltage amplification	V _O = ±10 V, R _L = ≥ 2 kΩ	25°C	50	160		25		160		25		160		V/mV
			Full range	25		15		15		15		15			
r _i	Input resistance‡		25°C	0.8	2.5		0.8		2.5		0.8		2.5		MΩ
B ₁	Unity-gain bandwidth	A _{VD} = 1	25°C	1			1			1			1		MHz
φ _m	Phase margin	A _{VD} = 1	25°C	60°			60°			60°			60°		
CMRR	Common-mode rejection ratio	V _{IC} = V _{ICRmin} , V _O = 0	25°C	70	90		70		90		70		90		dB
			Full range	70		70		70		70		70			
k _{SVR}	Supply-voltage rejection ratio (ΔV _{CC±} /ΔV _{IO})	V _{CC±} = ±9 V to ±15 V, V _O = 0	25°C	77	96		77		96		77		96		dB
			Full range	77		77		77		77		77			
I _{OS}	Short-circuit output current		25°C	±25			±25			±25			±25		mA
I _{CC}	Supply current (four amplifiers)	No load	25°C				2.4		4.5		2.4		4.5		mA
		V _O = V _{OM}		2.4		3.6									
V _{O1} /V _{O2}	Crosstalk attenuation	f = 1 Hz to 20 kHz	25°C	120			120			120			120		dB

[†] All characteristics are measured under open-loop conditions with zero common-mode input voltage, unless otherwise specified. Full range for T_A is -55°C to 125°C for LM148, -25°C to 85°C for LM248, and 0°C to 70°C for LM348.

[‡] This parameter is not production tested.

LM148, LM248, LM348

QUADRUPLER OPERATIONAL AMPLIFIERS

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operating characteristics, $V_{CC\pm} = \pm 15\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SR	Slew rate at unity gain	$R_L = 2\text{ k}\Omega$, $C_L = 100\text{ pF}$, See Figure 1		0.5		V/ μs

PARAMETER MEASUREMENT INFORMATION

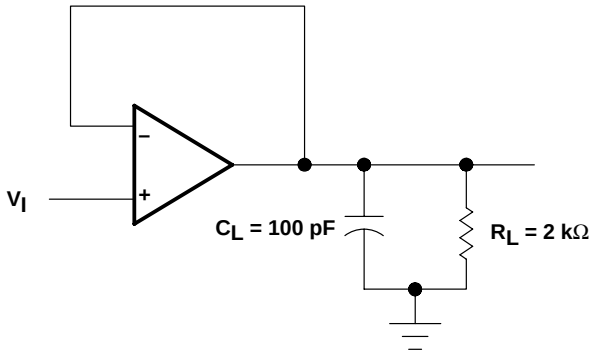


Figure 1. Unity-Gain Amplifier

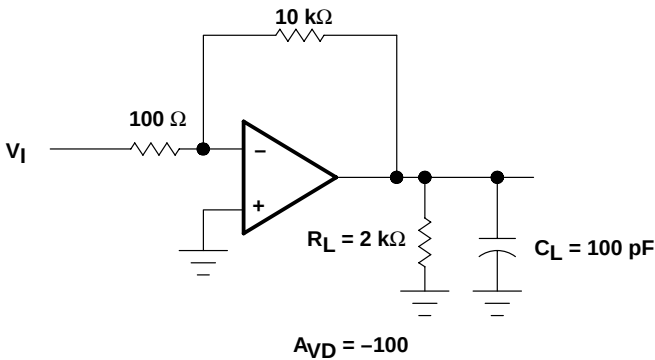


Figure 2. Inverting Amplifier

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
LM148FKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
LM148J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
LM148JB	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
LM248D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM248DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM248DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM248DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM248DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM248DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM248N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LM248NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LM348D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM348DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM348DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM348DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM348DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM348DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM348N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LM348NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LM348NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM348NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LM348NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

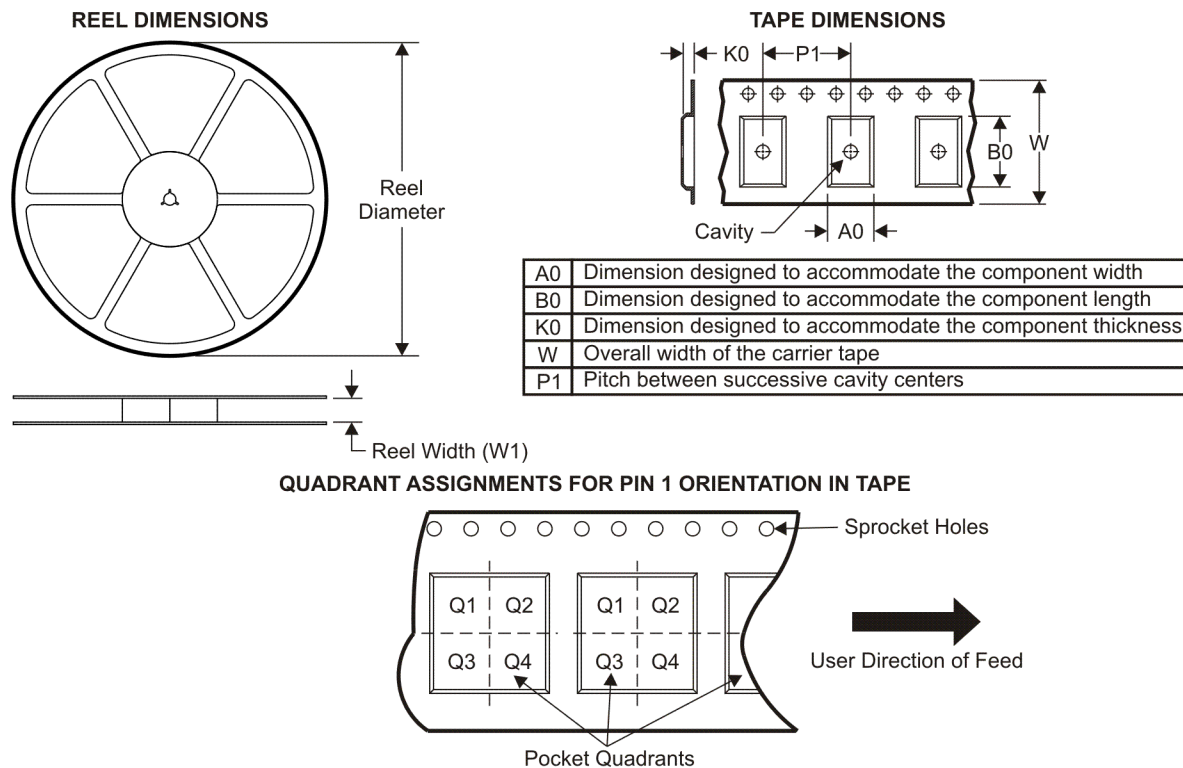
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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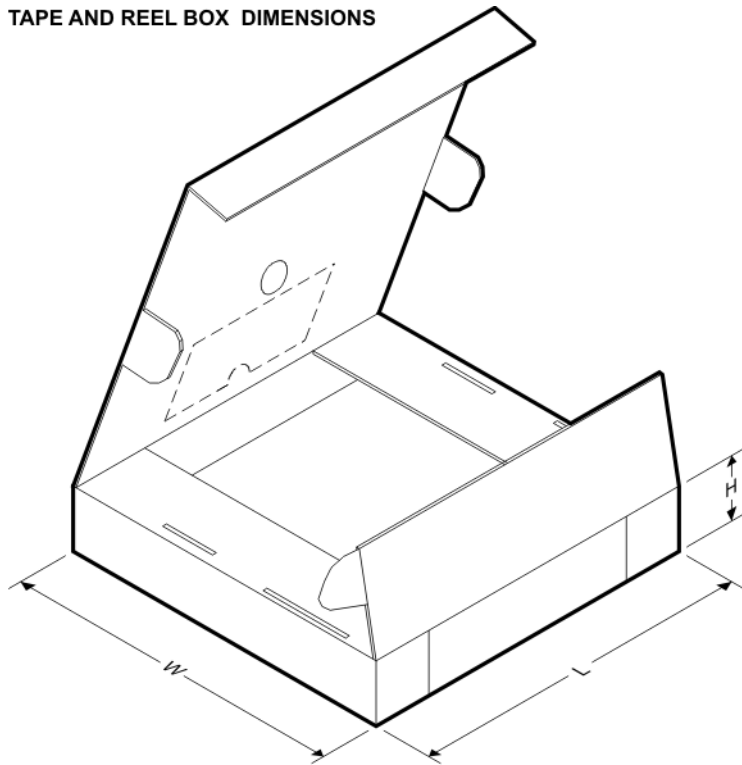
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM248DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM348DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM348DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM348NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



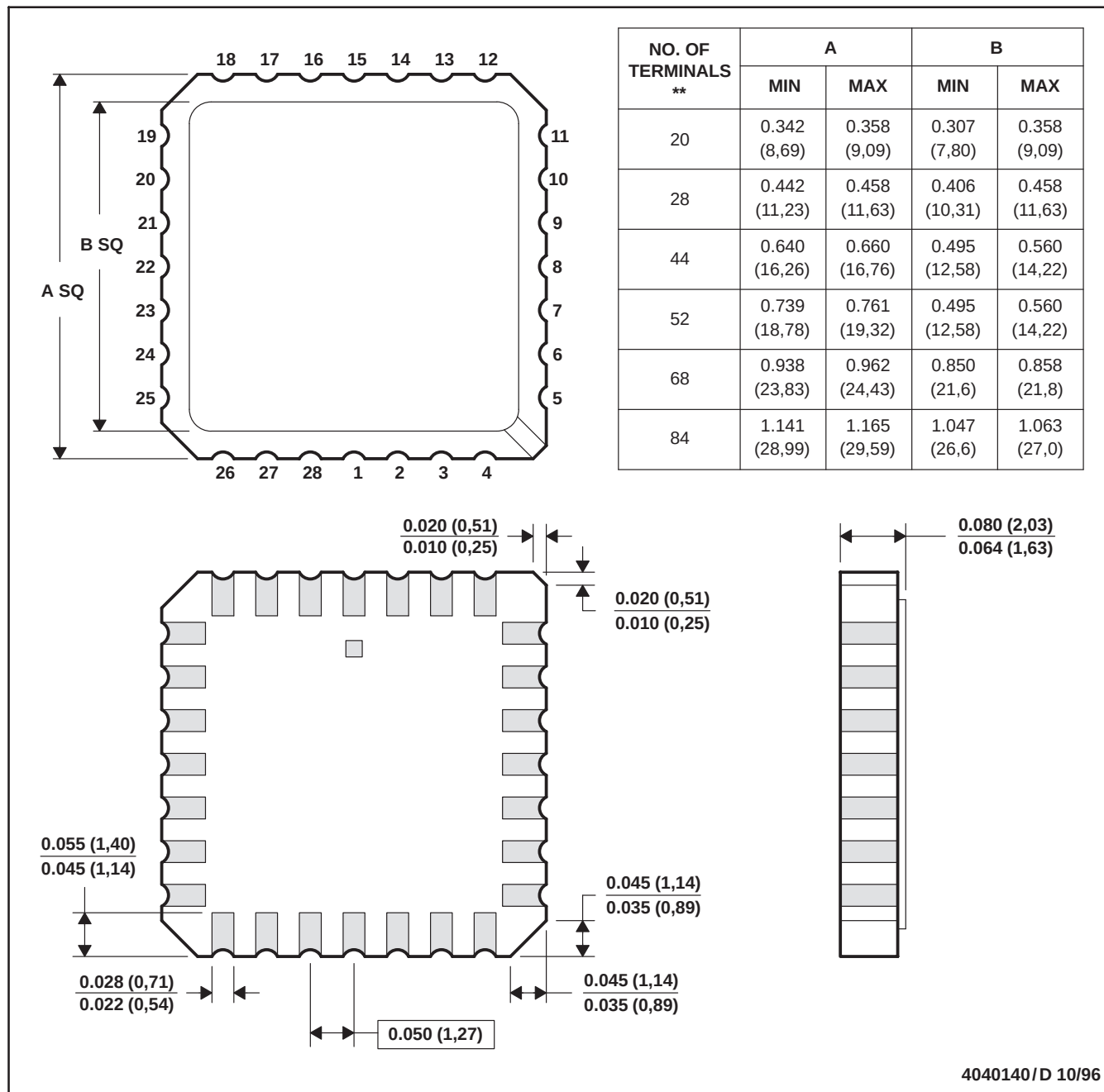
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM248DR	SOIC	D	14	2500	346.0	346.0	33.0
LM348DR	SOIC	D	14	2500	333.2	345.9	28.6
LM348DR	SOIC	D	14	2500	346.0	346.0	33.0
LM348NSR	SO	NS	14	2000	346.0	346.0	33.0

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN

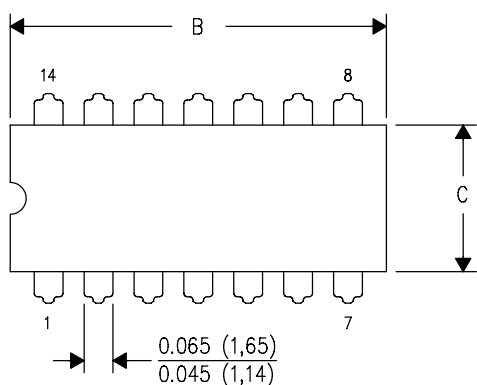


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - The terminals are gold plated.
 - Falls within JEDEC MS-004

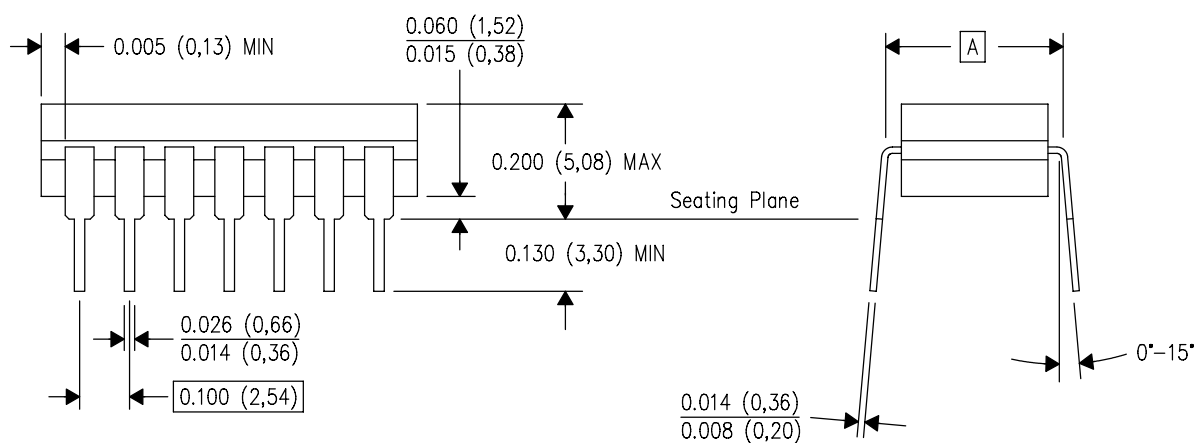
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

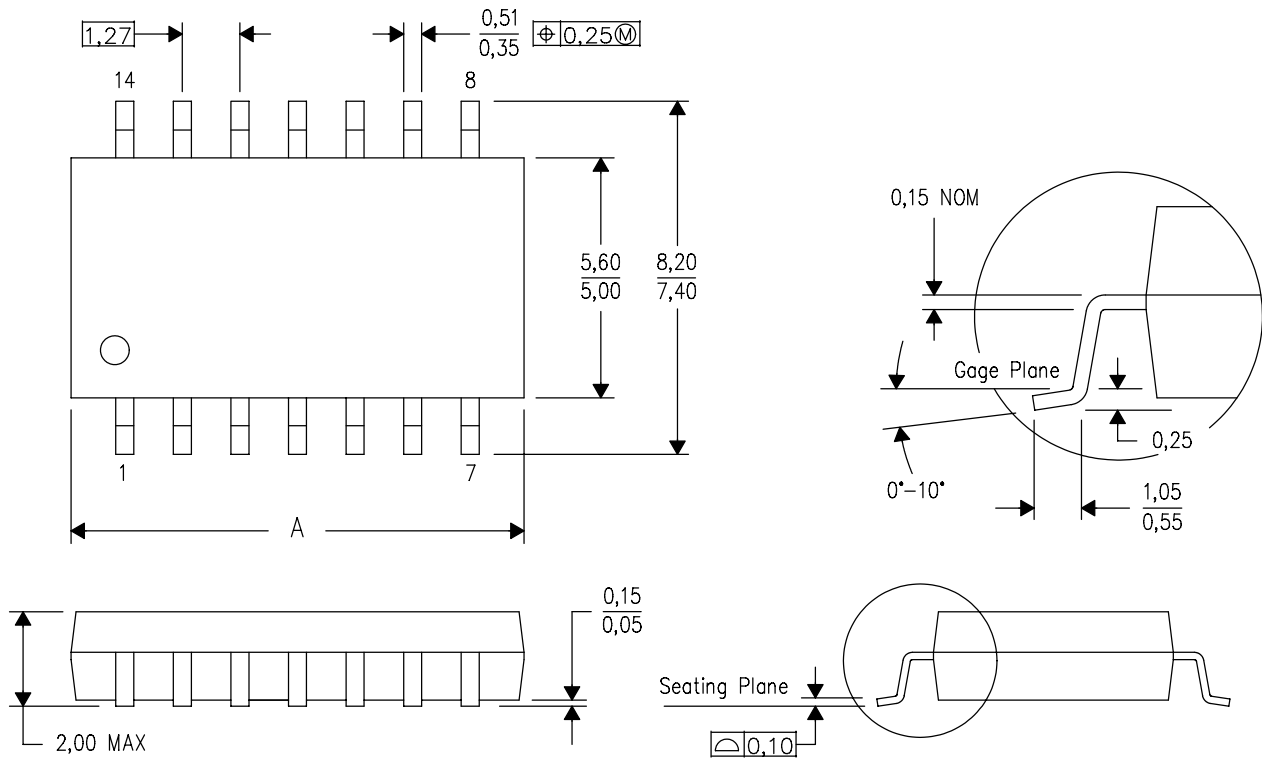
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



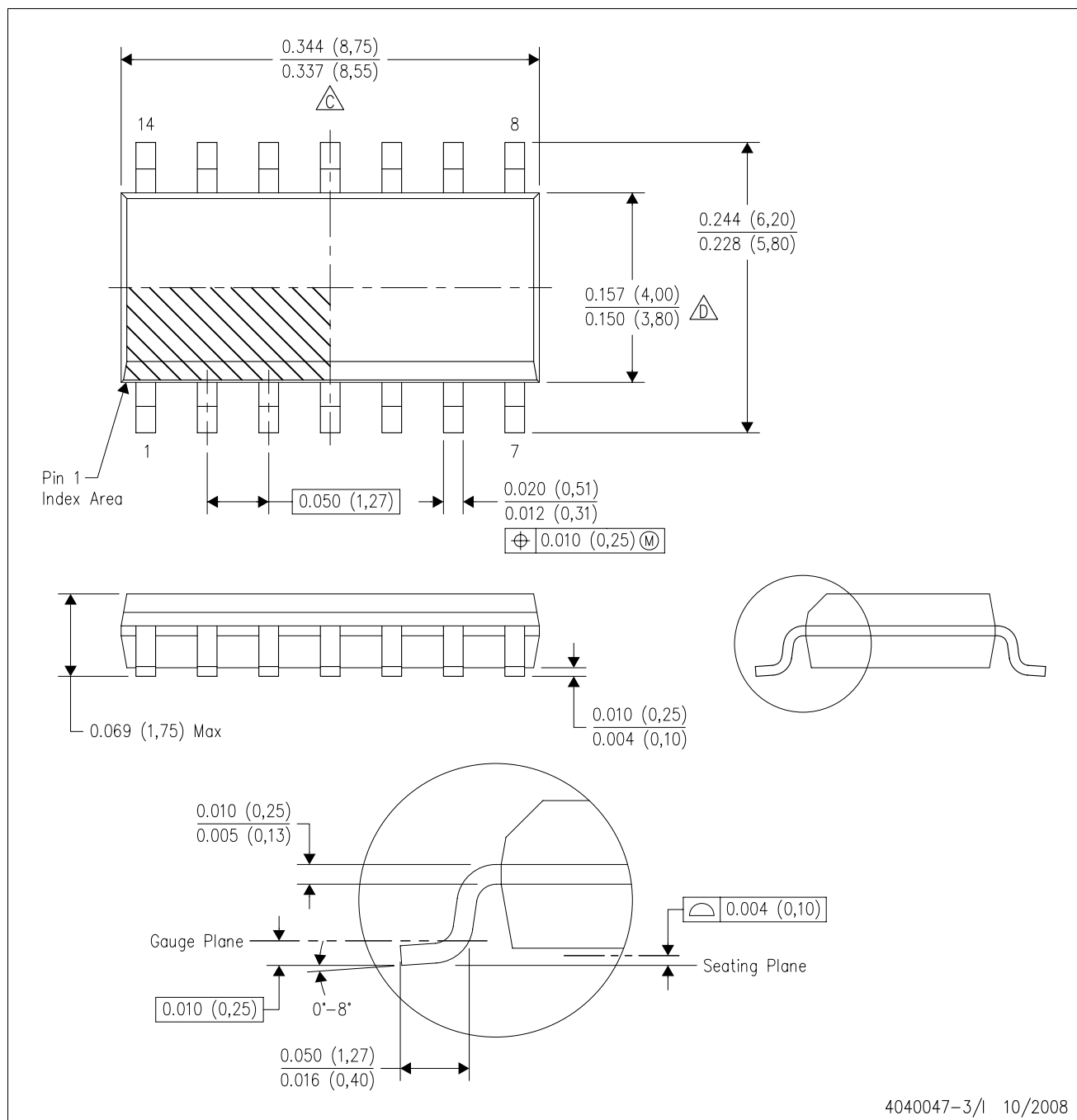
DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



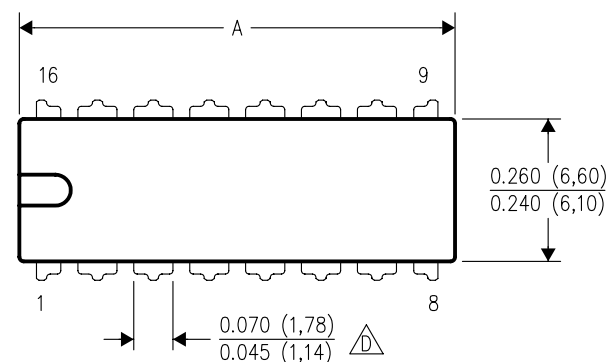
NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
D Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
E. Reference JEDEC MS-012 variation AB.

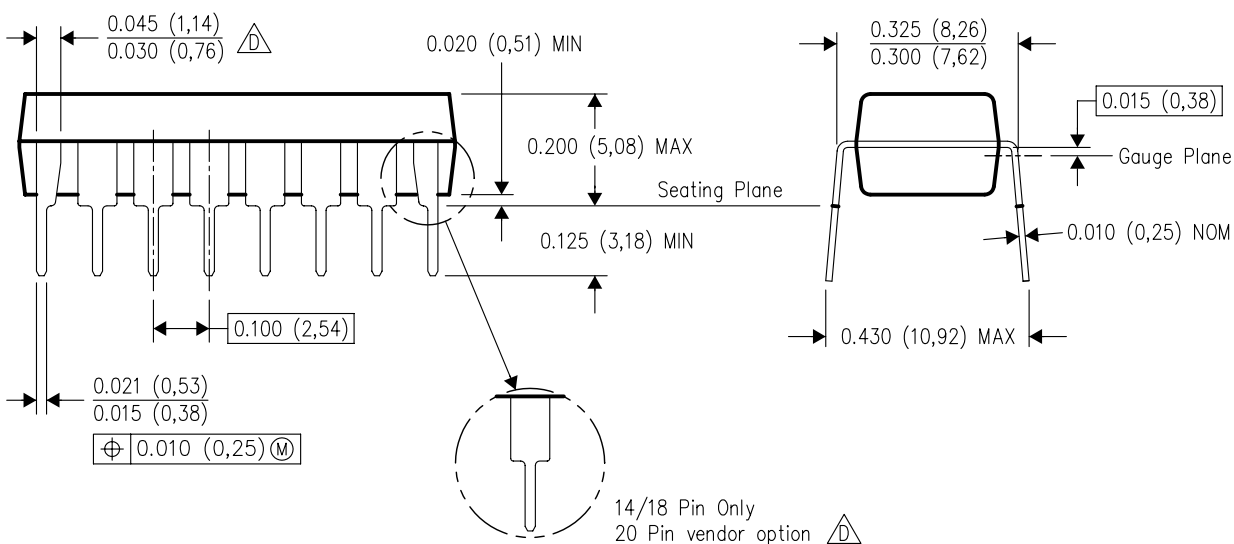
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 -  The 20 pin end lead shoulder width is a vendor option, either half or full width.